

09/922,770

L Number	Hits	Search Text	DB	Time stamp
1	352937	(transparent transmissive glass window optoelectronic) and @ad<19991212 and (semiconductor packag\$3 IC (integrated adj circuit) chip die dice)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/27 21:57
2	23053	((transparent transmissive glass window optoelectronic) and @ad<19991212 and (semiconductor packag\$3 IC (integrated adj circuit) chip die dice)) and spacer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/27 21:57
3	14421	((transparent transmissive glass window optoelectronic) and @ad<19991212 and (semiconductor packag\$3 IC (integrated adj circuit) chip die dice)) and spacer) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/27 21:58
4	7642	((transparent transmissive glass window optoelectronic) and @ad<19991212 and (semiconductor packag\$3 IC (integrated adj circuit) chip die dice)) and spacer) and substrate) and (cavity opening)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/27 22:00
5	307	((transparent transmissive glass window optoelectronic) and @ad<19991212 and (semiconductor packag\$3 IC (integrated adj circuit) chip die dice)) and spacer) and substrate) and (cavity opening)) and ((surface adj acoustic adj wave) SAW)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/27 22:01
6	23	((transparent transmissive glass window optoelectronic) and @ad<19991212 and (semiconductor packag\$3 IC (integrated adj circuit) chip die dice)) and spacer) and substrate) and (cavity opening)) and ((surface adj acoustic adj wave) SAW)) and (micromechanical mems)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/27 22:12
7	348	((438/7) or (438/116)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/27 22:12
8	208	((438/7) or (438/116)).CCLS.) and @ad<19991212	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/27 22:13
9	114	((438/7) or (438/116)).CCLS.) and @ad<19991212) and (gap opening cavity)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/27 22:14